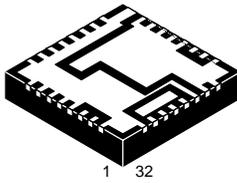


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

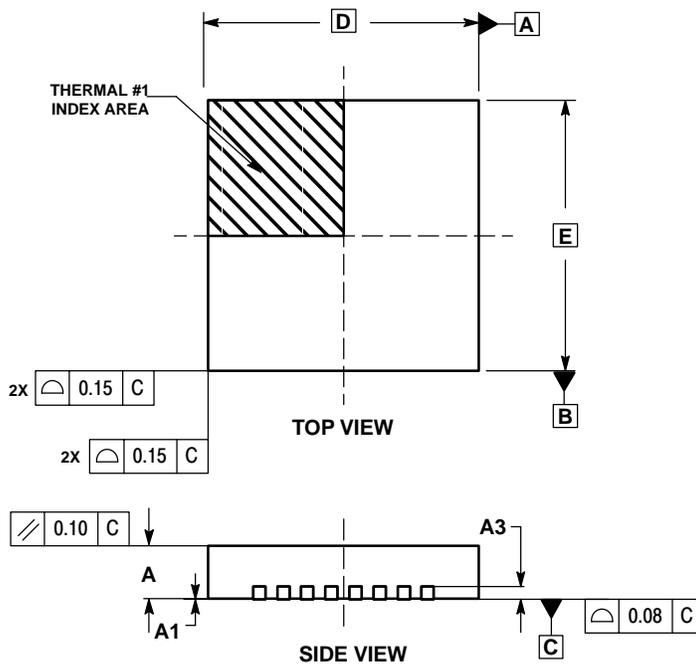
ON Semiconductor®



SCALE 2:1

PLL32  
CASE 488AC-01  
ISSUE A

DATE 23 JUN 2004

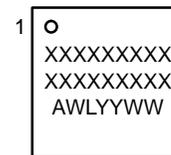


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 MM AND 40 MM FROM TERMINAL TIP
4. UNILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THEIR TERMINALS.

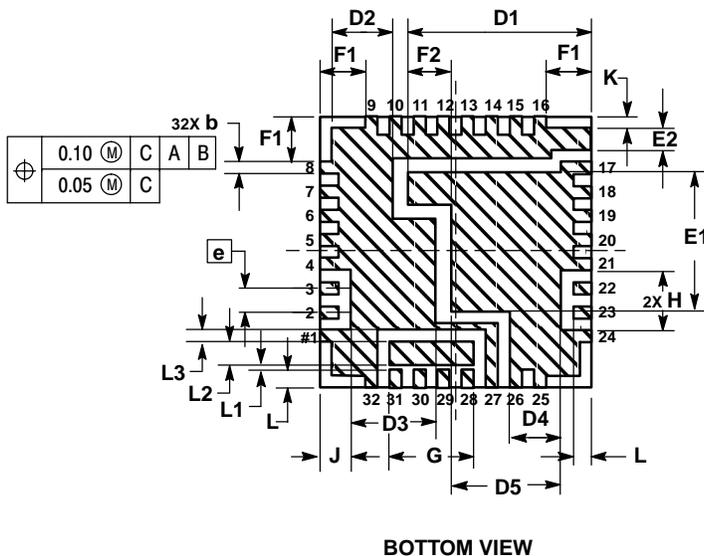
MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.750	1.850	1.950
A1	0.000	----	0.050
A3	0.254 REF		
b	0.350	0.400	0.450
D	9.000 BSC		
D1	5.987	6.087	6.187
D2	1.924	2.024	2.124
D3	2.713	2.813	2.913
D4	1.584	1.684	1.784
D5	3.547	3.647	3.747
E	9.000 BSC		
E1	4.472	4.572	4.672
E2	0.638	0.738	0.838
e	0.800 BSC		
F1	1.500 REF		
F2	1.324	1.424	1.524
G	2.700	2.800	2.900
H	2.000 REF		
J	1.016 BSC		
K	0.381 REF		
L	0.500	0.600	0.700
L1	0.062	0.162	0.262
L2	0.760	0.770	0.870
L3	0.281	0.381	0.481

GENERIC MARKING DIAGRAM\*



XXXXXXX= Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 YY = Year  
 WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present.



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	PLL32, 9X9X1.85 0.8 PITCH	PAGE 1 OF 2

